



Special instruction: Keep bonding for Xin and Xout as close to die cavity edge as possible as we will mount additional 0201 component in red oval area.

Chip size: 1.10 × 1.30mm
 Chip thickness: 300 ± 30µm
 PAD size: 150µm × 100µm (VCC, OUT, OUTN pins)
 100µm × 100µm (excluding VCC, OUT, OUTN pins)
 Chip base: GND potential
 Note: The TEST pin is not used during normal operation.

Instructions:

A. Standard process flow for die-attach and wire bond.
 B. Conductive silver paste 84-10MISR4 silver epoxy Ablestick is to be used for die attach.

C. Curing: Curing time: 8 Hr ± 20 / - 0 min

Curing temp: 160 ± 10°C

N2 Supply: 5 SCFH min.

Adhesive paste cure temperature is to be 160 degrees C for 8 hours minimum

D. Final assemblies to be nitrogen purged and vacuum packed for transportation. Trays used for shipping ceramic carriers are acceptable.

Notes:

CF5036 and CF5037 use the same bonding diagram

Item ID	Description	Qty per Assem
S5070DCK1	Sumitomo 6-pad 5x7mm pkg for NPC Differential output IC	1
CF5037C1-1	NPC IC	1
C0402K-103-PD	Capacitor 0402 0.01uF SMD	1

Revision	Date	Reason
A	2005/12/28	Update format for general publication
-	2005/11/23	Original Issue